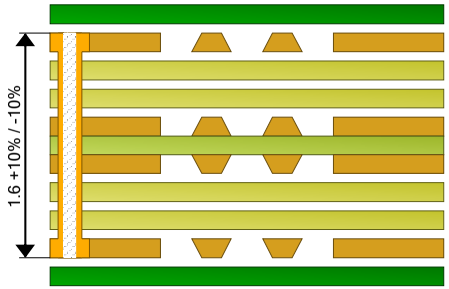
Layer	Stack up	Description	Base Thickness	Finish Thickness	Mask Thickness	εr	Impedance ID	Type	Notes-1
		Soldermask			0.020	4.100		SolderMask	10
1		Foil	0.012	0.035			1	Foil	0
		VT47-2116	0.120	0.120		4.150		PREPREG	
		VT47-2116	0.120	0.120		4.150		PREPREG	
2			0.018	0.018					
		VT-47	0.991	0.991		4.400		Core	
3			0.018	0.018					
		VT47-2116	0.120	0.120		4.150		PREPREG	
		VT47-2116	0.120	0.120		4.150		PREPREG	
4		Foil	0.012	0.035				Foil	0
		Soldermask			0.020	4.100		SolderMask	10

Copper Thickness = 0.106 | Dielectric Thickness = 1.471 | Solder Mask Thickness = 0.040 | Stack Up Thickness = 1.576 | Stack Up Thickness with Solder Mask = 1.616 |

Impedance ID	Structure Image	Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Broadside 2nd Layer	Calculated Impedance	Target Impedance	Tol (+/- %)
1		Coated Coplanar Waveguide With Lower Ground 1B	1	2	0	0.330	0.000	0.150	0	48.860	50.000	10.000

Column Position	Drill Image	1st Layer	2nd Layer	Drill Type	Fill Type	Minimum Size	Data Filenames
1		1	4	Mechanical PTH	None	0.200	